

# SOT2092-1

FBGA529, fine pitch ball grid array package, 529 terminals, 0.8 mm pitch, 19 mm x 19 mm x 1.64 mm body

25 November 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA529
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	05-10-2020
<b>Manufacturer package code</b>	98ASA01713D

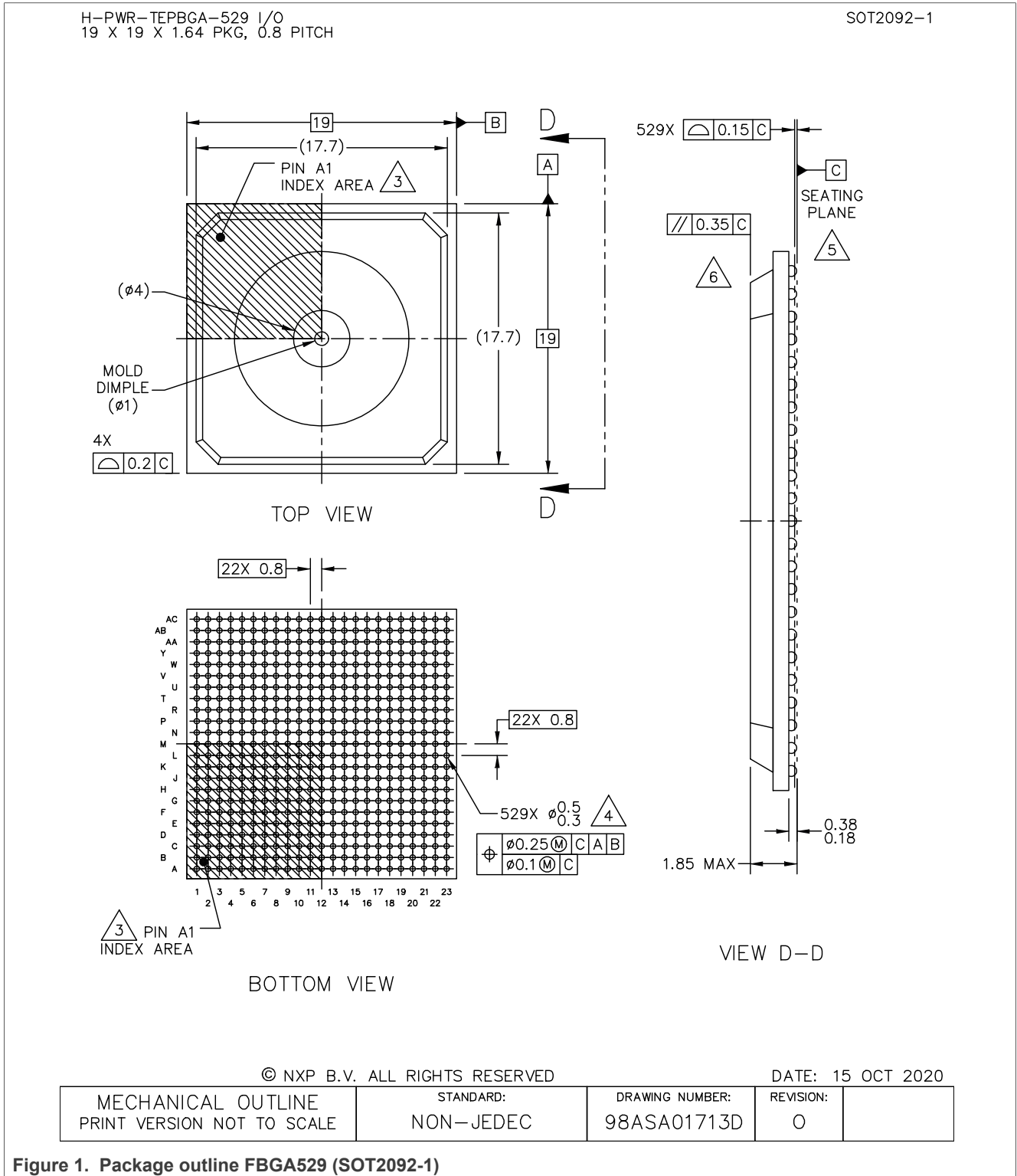
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	18.8	19	19.2	mm
package width	18.8	19	19.2	mm
package height	-	1.64	1.85	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	529	-	

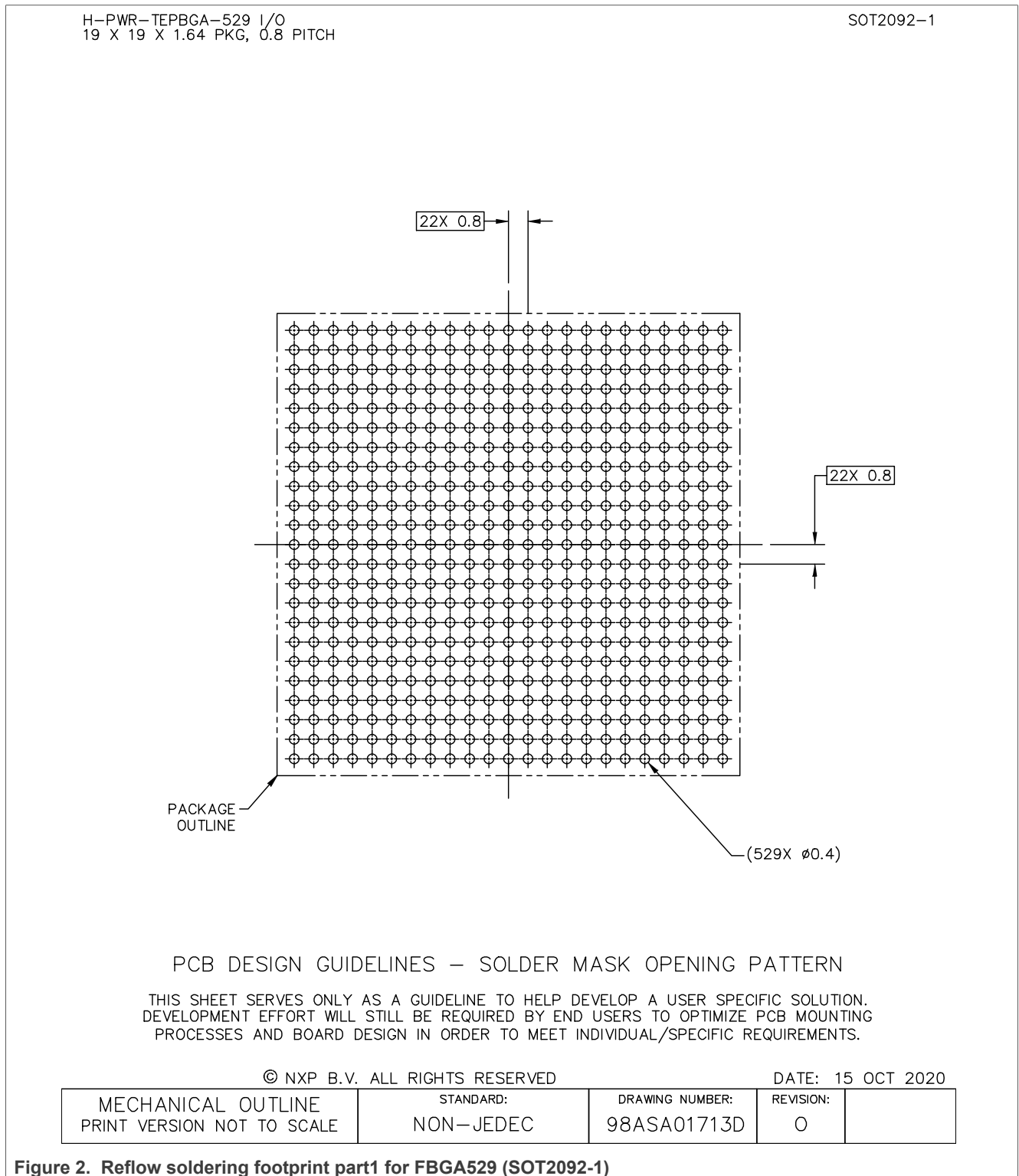


FPGA529, fine pitch ball grid array package, 529 terminals, 0.8 mm pitch, 19 mm x 19 mm x 1.64 mm body

2 Package outline

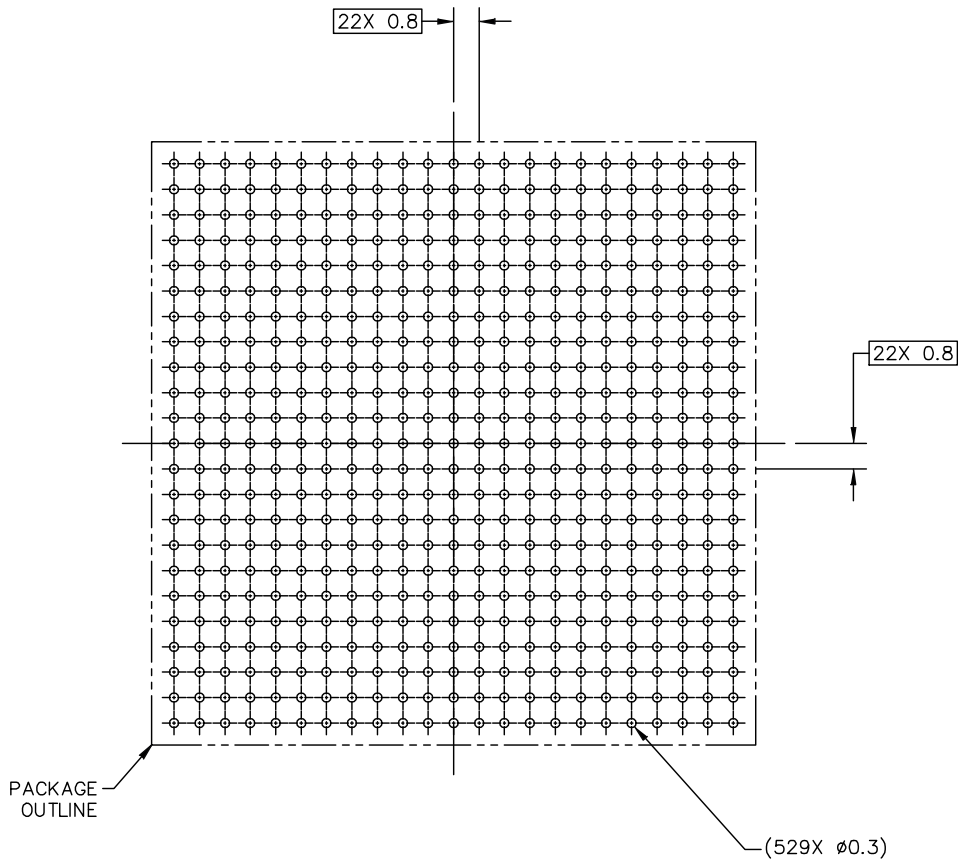


3 Soldering



H-PWR-TEPBGA-529 I/O  
19 X 19 X 1.64 PKG, 0.8 PITCH

SOT2092-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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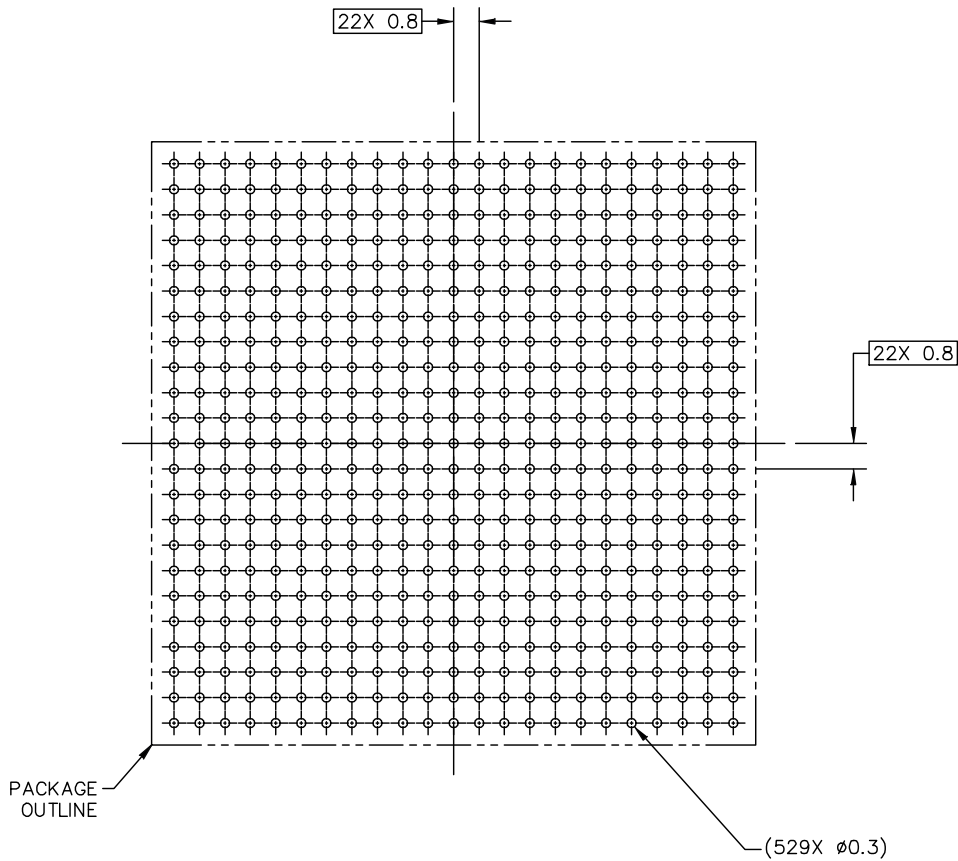
DATE: 15 OCT 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01713D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for FBGA529 (SOT2092-1)

H-PWR-TEPBGA-529 I/O  
19 X 19 X 1.64 PKG, 0.8 PITCH

SOT2092-1



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for FBGA529 (SOT2092-1)

FBGA529, fine pitch ball grid array package, 529 terminals, 0.8 mm pitch, 19 mm x 19 mm x 1.64 mm body

H-PWR-TEPBGA-529 I/O  
19 X 19 X 1.64 PKG, 0.8 PITCH

SOT2092-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note FBGA529 (SOT2092-1)

## 4 Legal information

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**Contents**

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1 Package summary .....1  
2 Package outline .....2  
3 Soldering .....3  
4 Legal information .....7